

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF40A W2 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2004-9-26 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



### 1. SCOPE

This specification shall cover the characteristics of SAW filter With F49A used for the E-amps/adc.

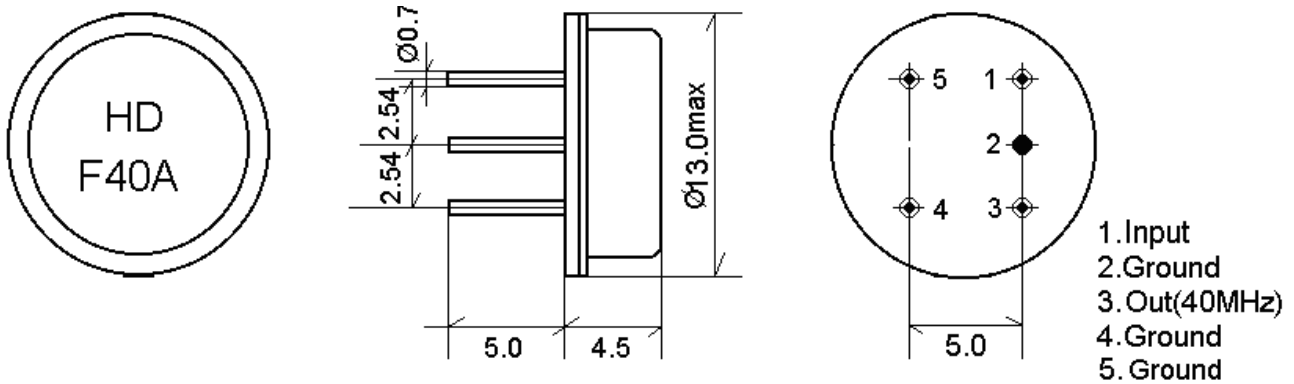
### 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

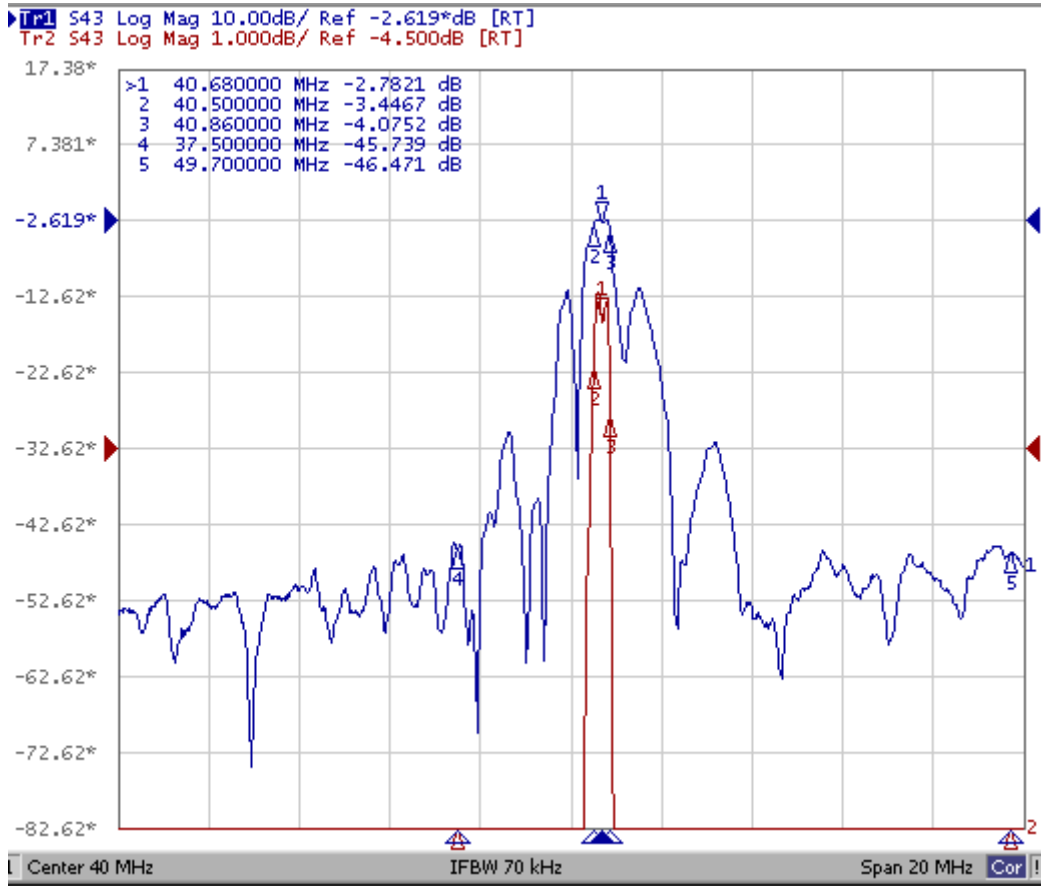
#### 2.2 Electronic Characteristics

Item	Freq	min	typ	max	
Nominal frequency	$f_N$	-	40.68	-	MHz
Insertion attenuation 40.50~40.86MHz			3.5	4.5	dB
attenuation	20.00~37.50MHz	30.0	35.0		dB
	49.70~50.02MHz	30.0	47.0		dB
	50.02~80.00MHz	30.0	35.0		dB
Temperature coefficient		-72			ppm/k

### 3. DIMENSION



### 4. Typical Frequency Response



### 5. ENVIRONMENTAL CHARACTERISTICS

#### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

#### 5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

#### 5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

#### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

#### 5-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95%

area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

#### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

#### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

## 6. REMARK

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.